



US00D517072S

(12) **United States Design Patent** (10) **Patent No.:** **US D517,072 S**  
**Yamada et al.** (45) **Date of Patent:** **\*\* Mar. 14, 2006**

(54) **IC MEMORY CARD**

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(\*\*) Term: **14 Years**

(21) Appl. No.: **29/169,127**

(22) Filed: **Oct. 15, 2002**

(51) **LOC (8) Cl.** ..... **14-02**

(52) **U.S. Cl.** ..... **D14/436**

(58) **Field of Classification Search** ..... D14/432-439, D14/478-480; 361/736-737, 686, 752; 257/678, 257/679; 40/124.01; 283/75-76, 901; 235/489, 235/495, 441-443, 375; 174/52.1; 439/135, 439/140, 76.1

See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

D444,473 S	*	7/2001	Okamoto et al.	.....	D14/436
D445,111 S		7/2001	Okamoto et al.		
D446,525 S	*	8/2001	Okamoto et al.	.....	D14/436
D475,056 S	*	5/2003	Taniguchi et al.	.....	D14/436
D476,011 S	*	6/2003	Taniguchi et al.	.....	D14/436

**FOREIGN PATENT DOCUMENTS**

JP 1085565 9/2000

**OTHER PUBLICATIONS**

U.S. Design Appl. No. 29/169,130 filed on Oct. 15, 2002, 38 pages.

\* cited by examiner

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(57) **CLAIM**

The ornamental design for an IC memory card, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of the first embodiment of an IC memory card showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

FIG. 4 is a left side view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof;

FIG. 8 is a cross sectional view along the line 8—8 in FIG. 2;

FIG. 9 is a cross sectional view along the line 9—9 in FIG. 2;

FIG. 10 is a perspective view of a second embodiment of the IC memory card;

FIG. 11 is a front elevational view of FIG. 10;

FIG. 12 is a rear elevational view of FIG. 10;

FIG. 13 is a left side elevational view of FIG. 10;

FIG. 14 is a right side elevational view FIG. 10;

FIG. 15 is a top plan view of FIG. 10;

FIG. 16 is a bottom plan view of FIG. 10;

FIG. 17 is a cross sectional view taken along the line 17—17 in FIG. 11; and,

FIG. 18 is a cross sectional view taken along the line 18—18 in FIG. 11.

The interior details are omitted for clarity of illustration in FIGS. 8, 9, 17 and 18.

**1 Claim, 18 Drawing Sheets**

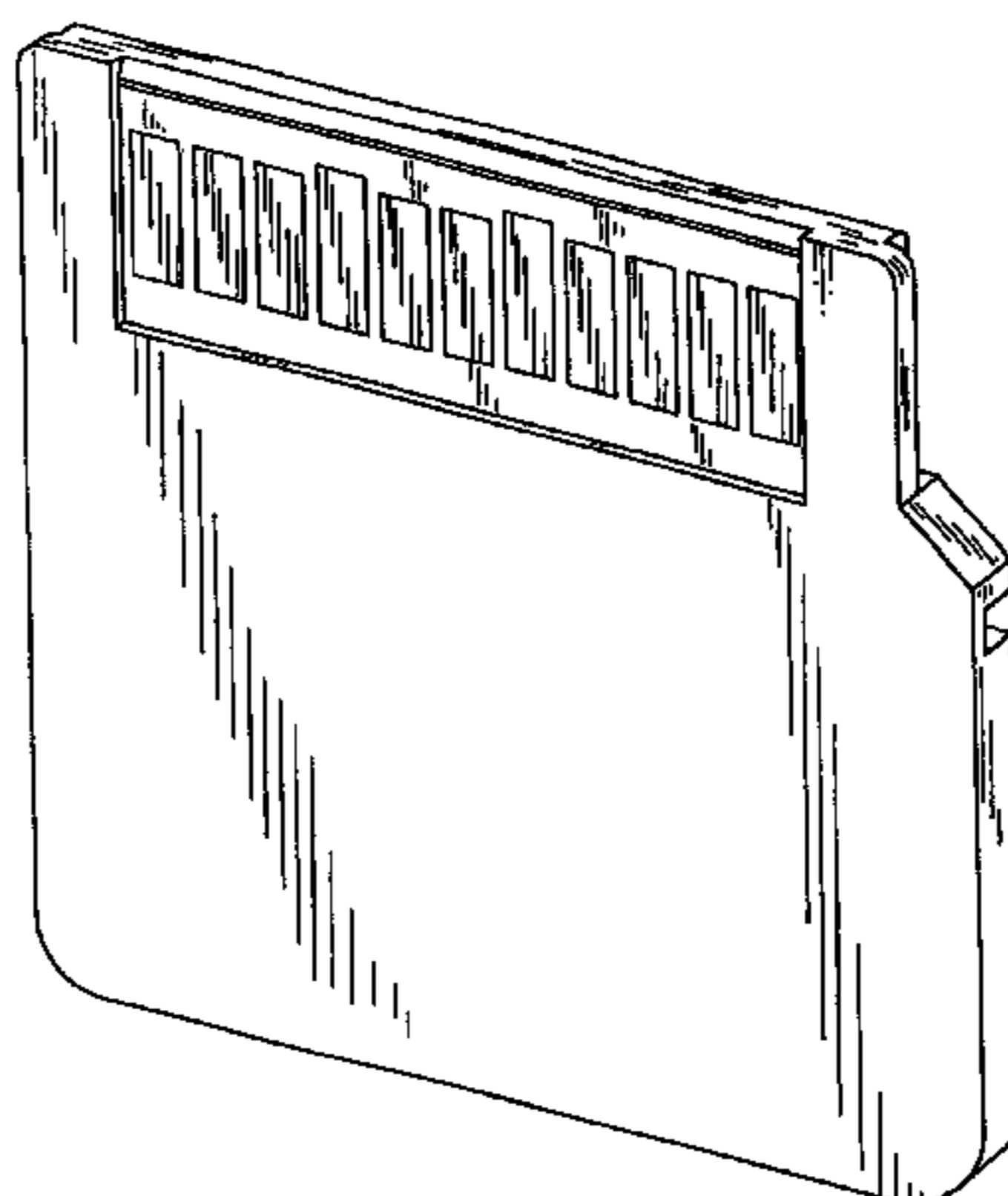


Fig. 1

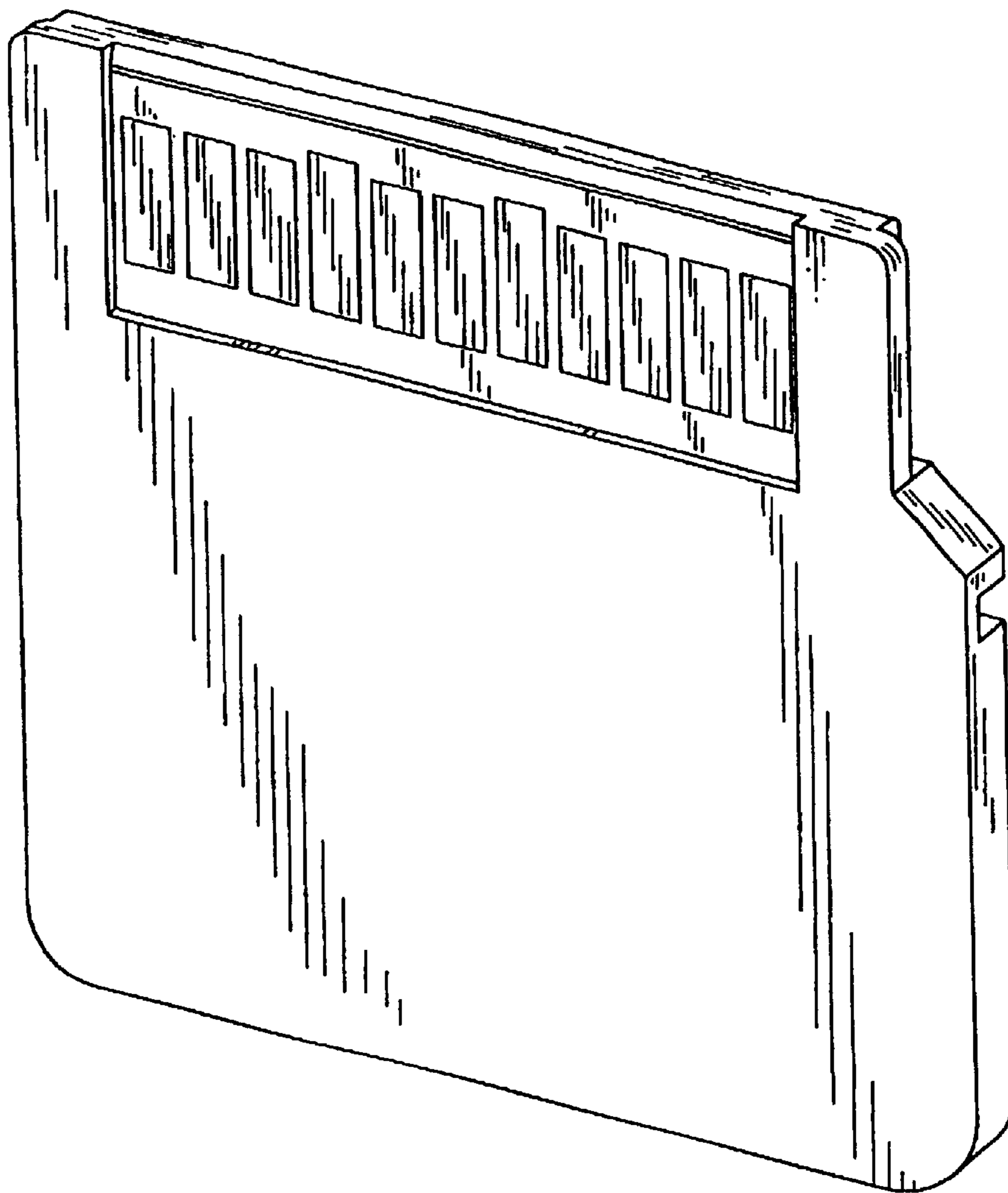


Fig. 2

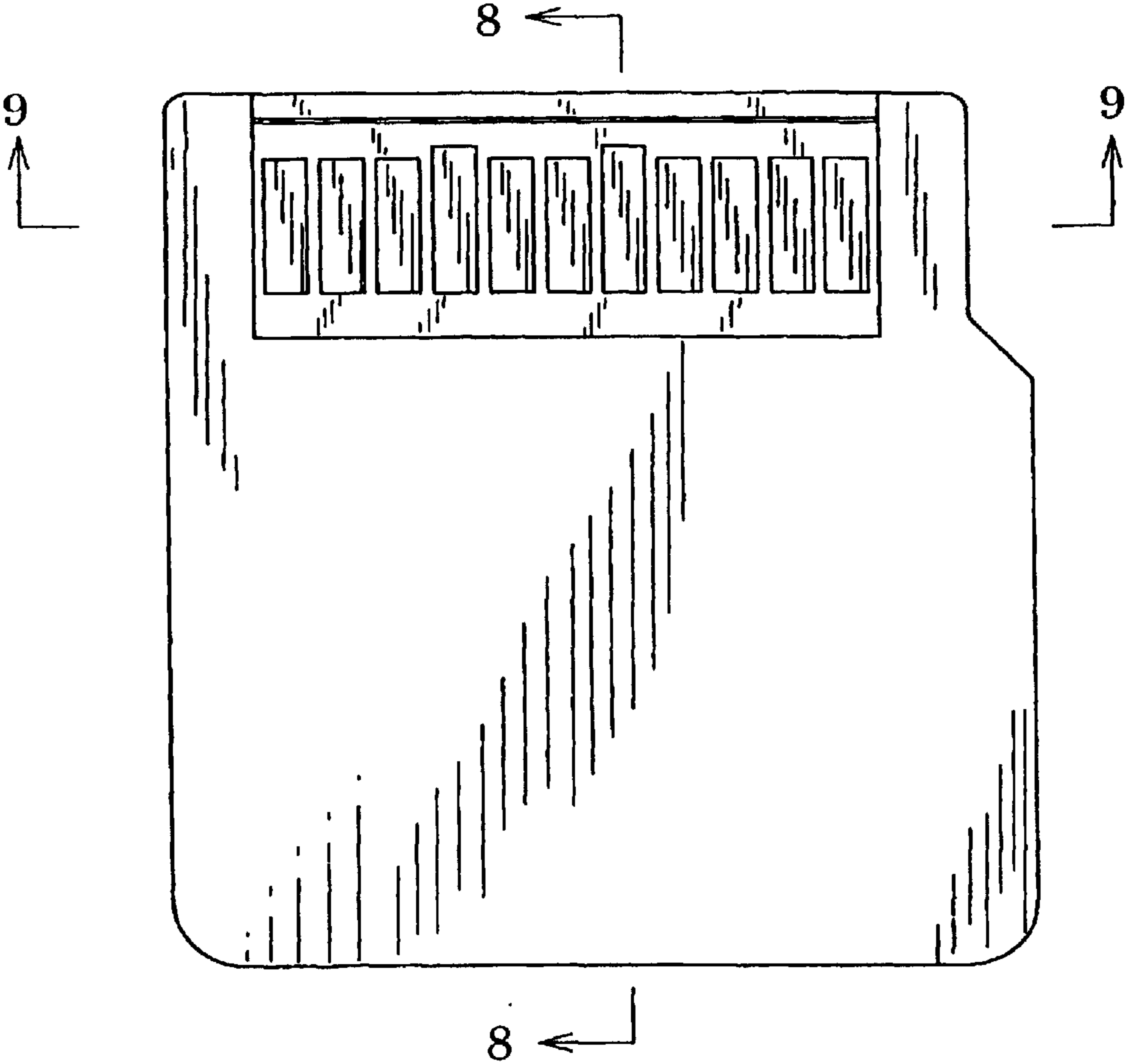


Fig. 3

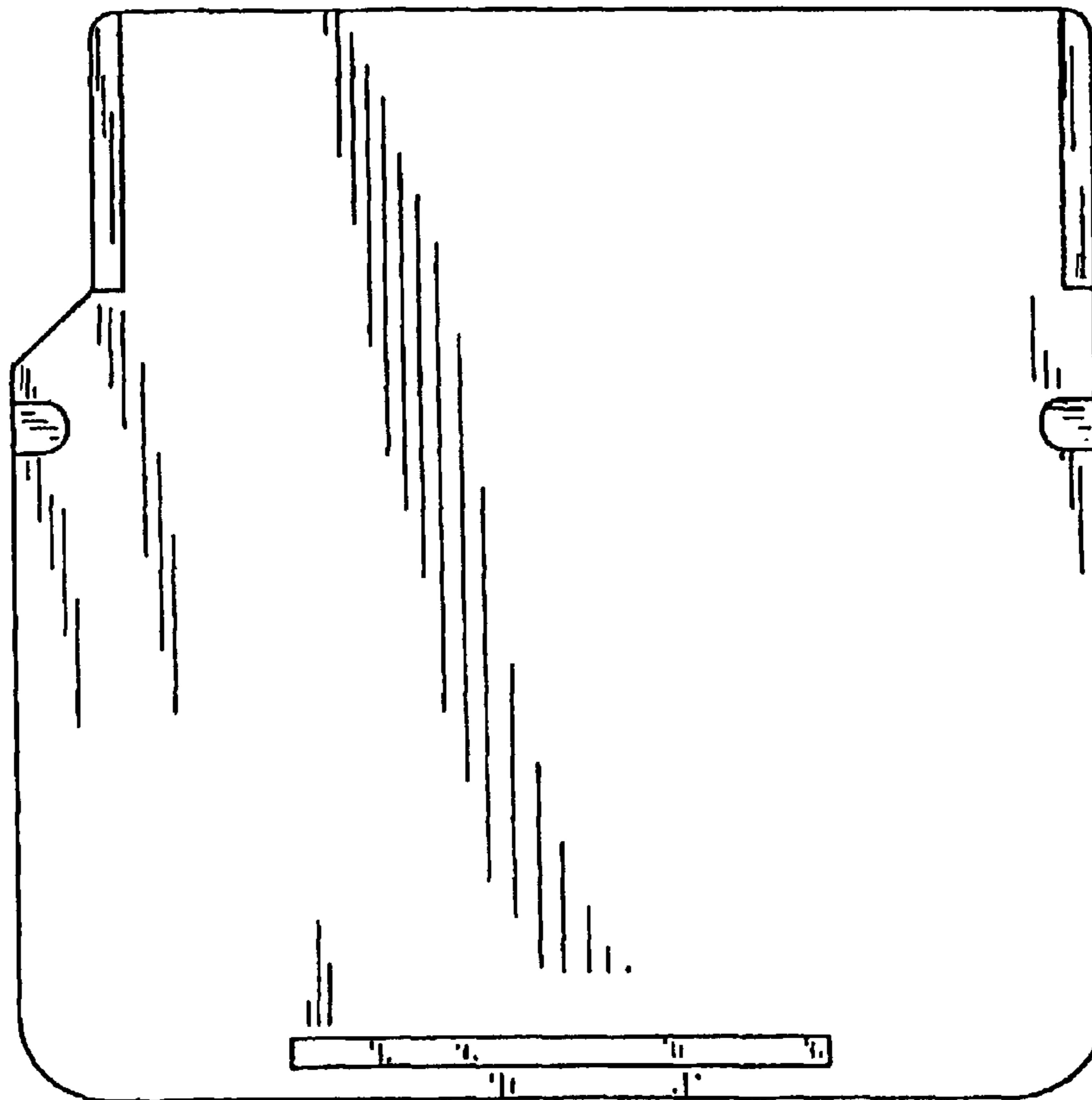


Fig. 4



Fig. 5



Fig. 6

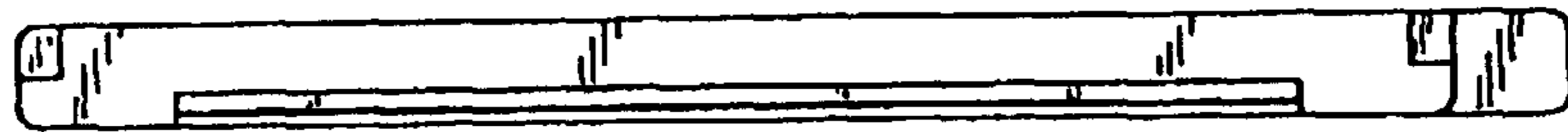


Fig. 7

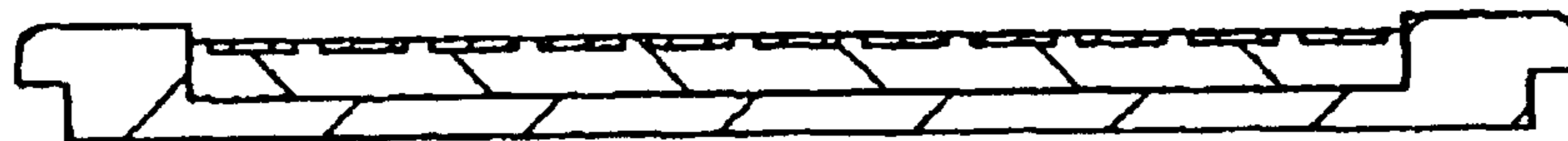




Fig. 8



Fig. 9



**FIG. 10**

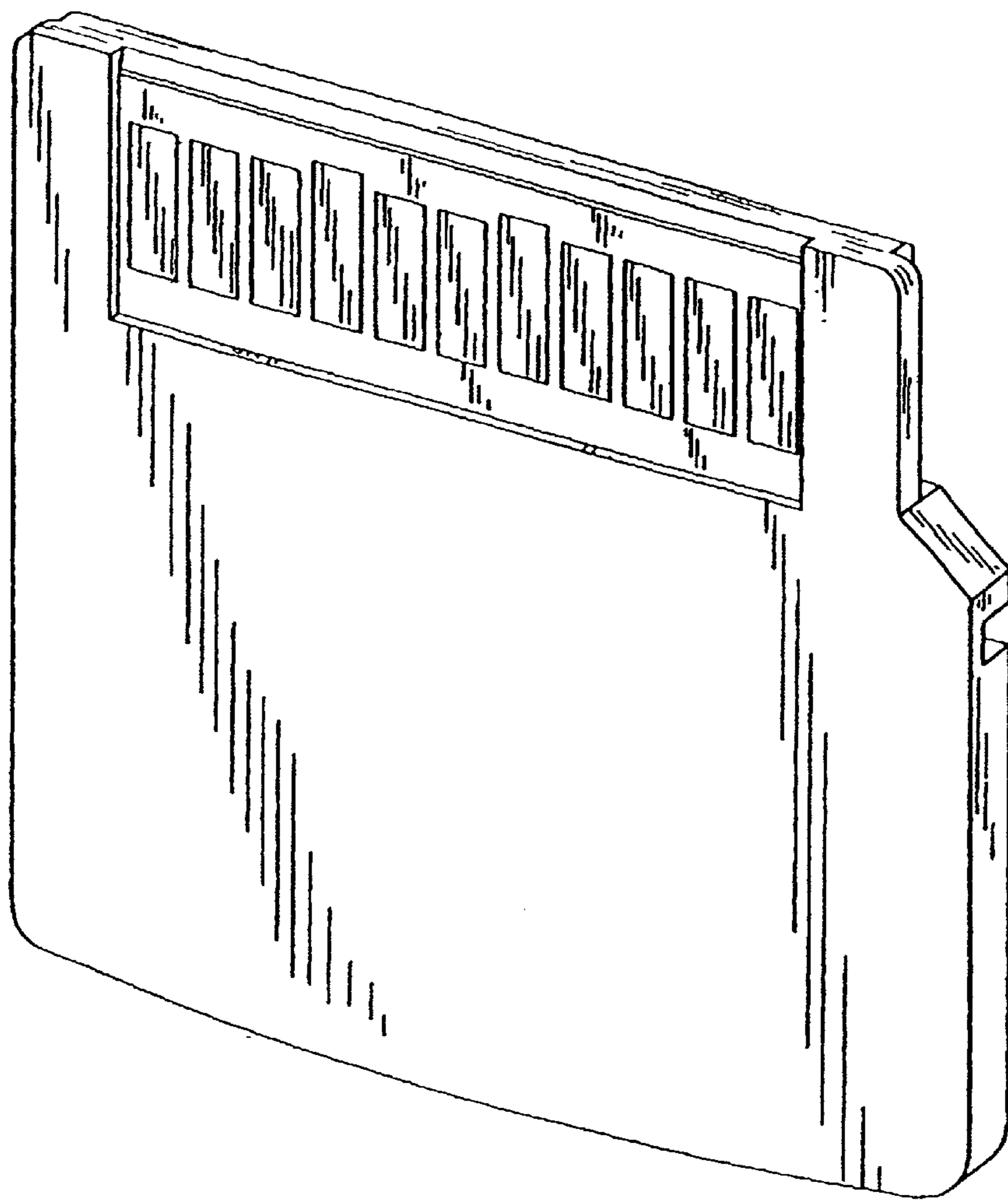
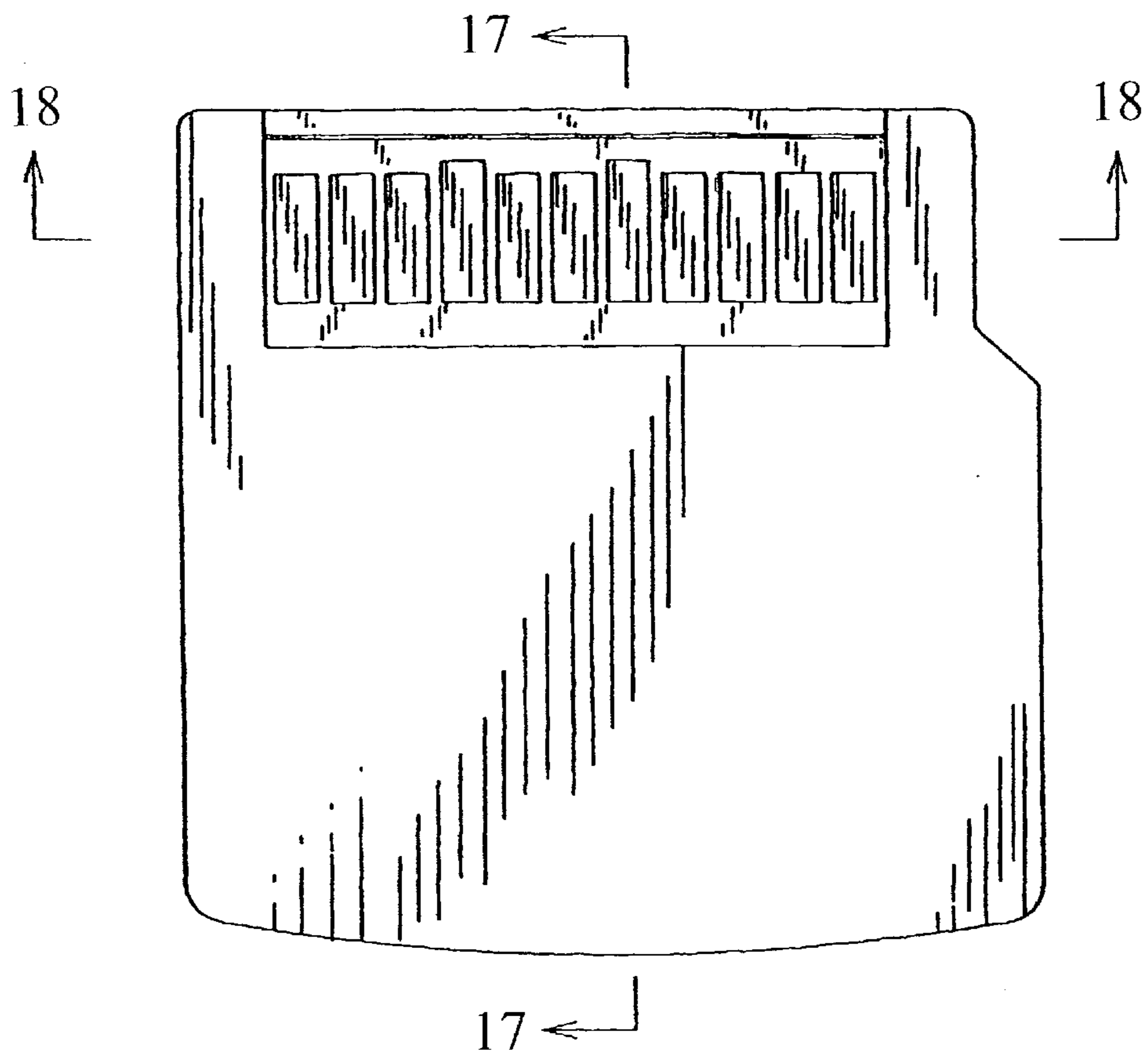
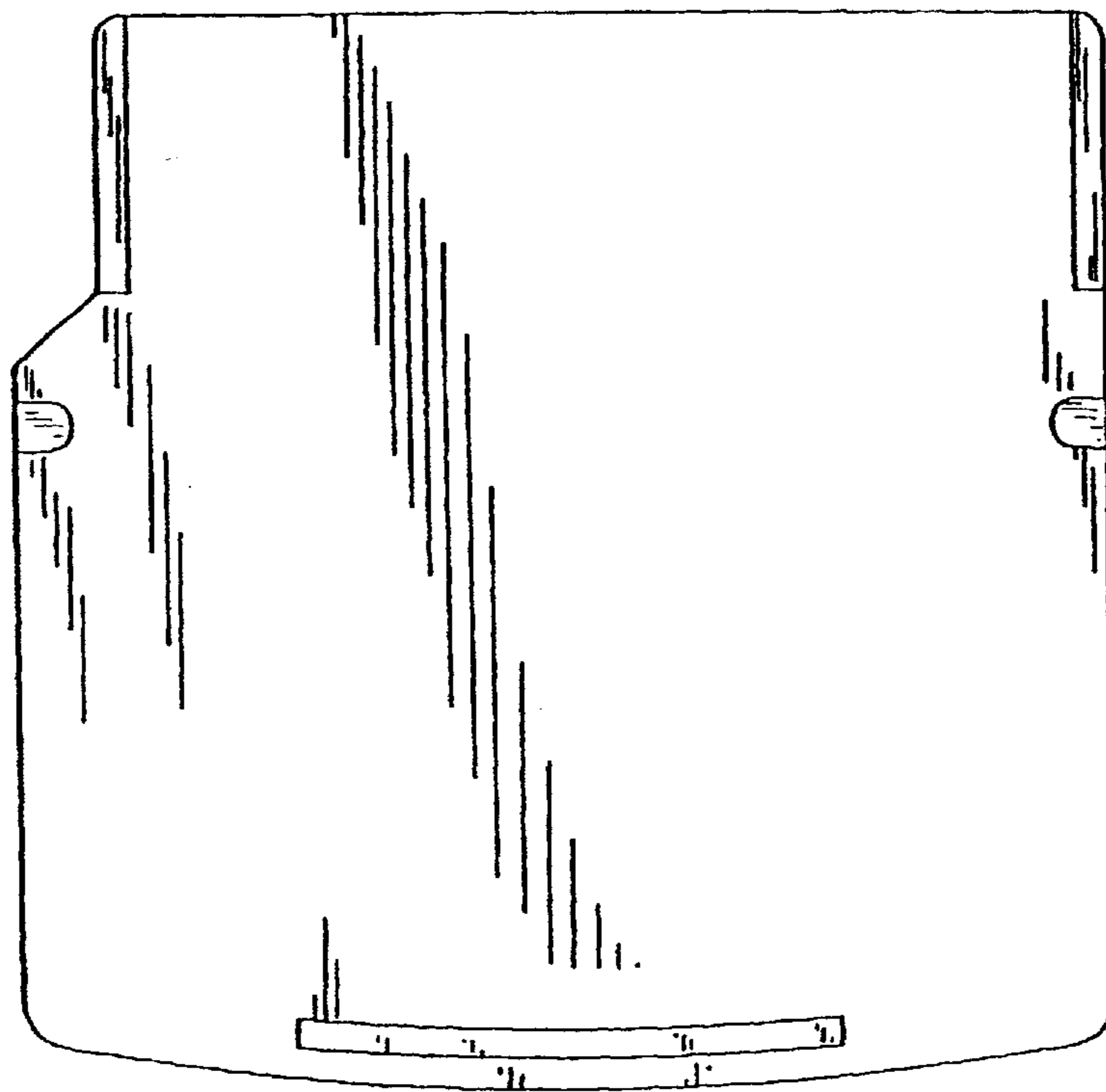


FIG. 11



**FIG. 12**



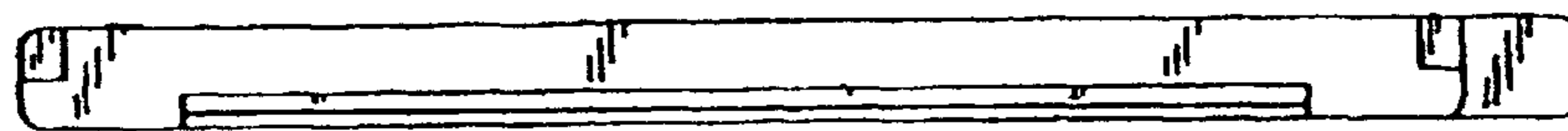
# FIG. 13



# FIG. 14



**FIG. 15**





**FIG. 16**



**FIG. 17**



**FIG. 18**

